

Bill of Materials

TI DESIGNS

Automotive Ultrasonic Sensor Interface for Park Assist or Blind Spot Detection Systems

Footprint	Comment	LibRef	Designator	Description	Quantity
0603 (HAND SOLDER)	0.1uF	CAPACITOR -NONPOLARIZED	C1, C2, C3, C5, C6, C7	0603,50V,10%,X7R	6
0603 (HAND SOLDER)	1500pF	CAPACITOR -NONPOLARIZED	C8	0805,250V,20%,NPO	1
CAP 6.6 X 6.6 MM SMD	100uF	CAPACITOR - POLARIZED	C9	SMT,35V,20%,AL	1
Diode_0603	CD0603-B0240	CD0603-B0240	D1	Diode, Schottky, 45V, 0.2A, 0603 Diode	1
0805_LED	LED - green	DIODE - LED	D2		1
0805_LED	LED - yellow	DIODE - LED	D3		1
0805_LED	LED	DIODE - LED	D4		1
0805_LED	LED - red	DIODE - LED	D5		1
HDR100_1X4	HEADER_1X4	HEADER_1X4	J1, J2	Header, Male 4-pin, 100mil spacing,	2
HDR100_1X2	HEADER_1X2	HEADER_1X2	J3, J4	Header, Male 2-pin, 100mil spacing,	2
0603 (HAND SOLDER)	100.0k	RESISTOR	R1	0603,1/10W,0.1%,+25ppm/C	1
0603 (HAND SOLDER)	2.7k	RESISTOR	R2	0603,1/10W,5%	1
2010 (hand solder)	3.3k	RESISTOR	R3	1210,1/4W,5%,+200ppm/C	1
0603 (HAND SOLDER)	0R DNP	RESISTOR	R4	0603,1/8W,5%	1
0603 (HAND SOLDER)	0R	RESISTOR	R5	0603,1/4W,5%	1
Transformer-Push Pull Toko	XFMR	Transformer Push-Pull	TR1	5-Pin Push-Pull XFMR	1
PW (R-PDSO-G28)	PGA450TPWRQ1	PGA450-Q1	U1	ULTRASONIC SENSOR SIGNAL CONDITIONER	1

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